

6-bit 140 MSPS Flash A/D Converter

Description

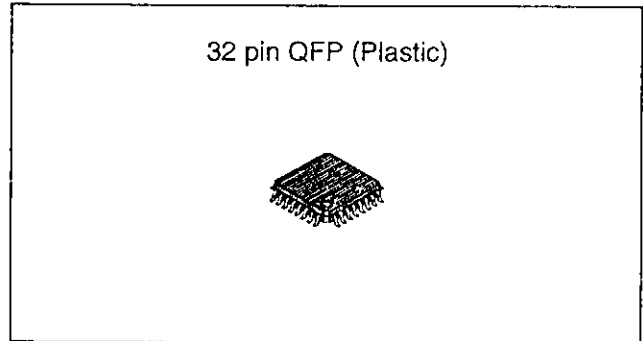
The CXA1826Q is a 6-bit high-speed flash A/D converter IC capable of digitizing analog signals at the maximum rate of 140 MSPS. The digital input/output level is compatible with the ECL 100K/10KH/10K.

Features

- Ultra-high speed operation with maximum conversion rate of 140 MSPS
- Low input capacitance
- Wide analog input bandwidth
- Low power consumption
- Low error rate

Function

6-bit 140 MSPS flash AD converter



Structure

Bipolar silicon monolithic IC

Applications

CRT PRML QAM

Absolute Maximum Ratings (Ta = 25°C)

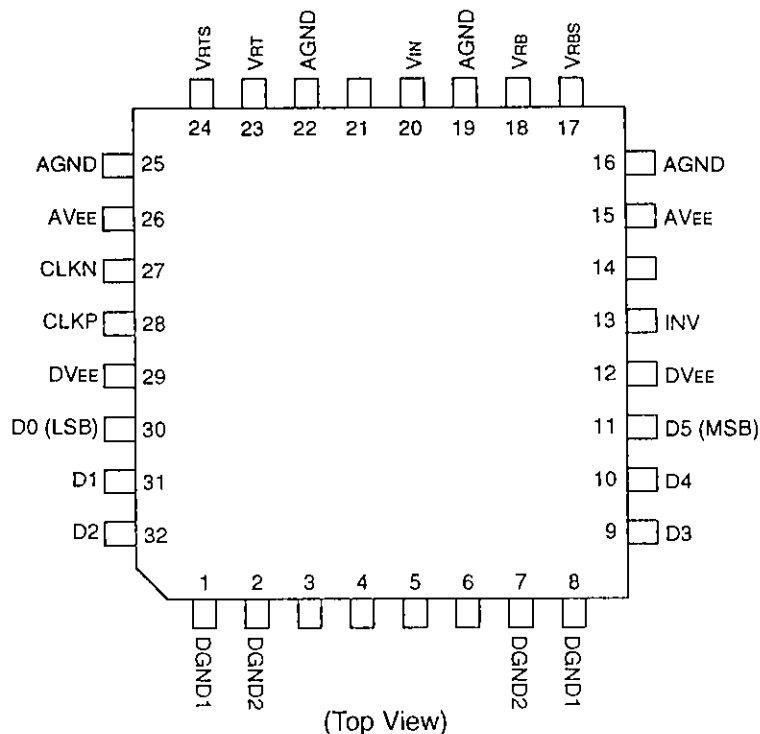
• Supply voltage	AVEE, DVEE	-7 to +0.5	V
• Analog input voltage	VIN	-2.7 to +0.5	V
• Reference input voltage	VRT, VRB	-1.5 to +0.5	V
	VRT-VRB	2.5	V
• Digital input voltage	CLKP, CLKN, INV	-4 to +0.5	V
	CLKP-CLKN	2.7	V
• Digital output current	ID0 to ID5	-30 to 0	mA
• Storage temperature	Tstg	-65 to +150	°C

Recommended Operating Conditions Min. Typ. Max.

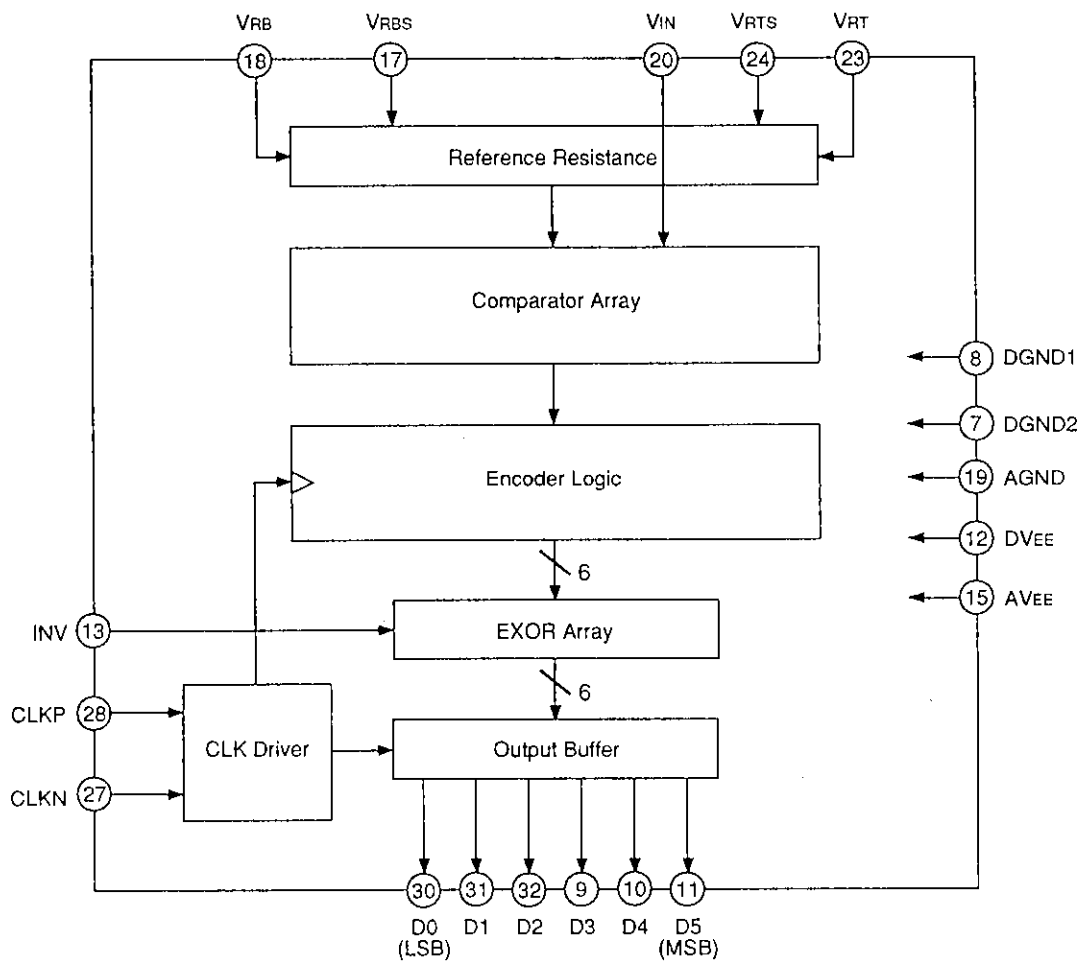
• Supply voltage	AVEE, DVEE	-5.5	-5.2	-4.95	V
	AVEE-DVEE	-0.05	0	0.05	V
	AGND-DGND	-0.05	0	0.05	V
• Reference input voltage	VRT	-0.1	0	0.1	V
	VRB	-2.2	-2.0	-1.8	V
• Analog input voltage	VIN	VRB		VRT	
• Pulse width of clock	TPW1	3.0			ns
	TPW0	3.0			ns
• Operating temperature	Ta	-20		75	°C

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Pin Configuration Pins without name are NC pins (not connected).



Block Diagram



Pin Description and I/O Pin Equivalent Circuit

Pin No.	Symbol	I/O	Typical voltage level	Equivalent circuit	Description
16, 19, 22, 25	AGND	—	0V		Analog GND. Used as GND for input buffers and latches of comparators. Separated from DGND1 and DGND2.
15, 26	AVEE	—	-5.2V		Analog VEE. Typical voltage is -5.2V. Connected internally with DVEE. (Resistance is 4 to 6 Ω.) Connect to AGND through a ceramic chip capacitor of 0.1 μF or more just near the pin.
28	CLKP	I	ECL		CLK input.
27	CLKN				CLK complementary input. When left open, voltage goes to ECL threshold potential (-1.3V). Although only CLKP input can be used for operation with CLKN input open, complementary input is recommended in order to attain high speed and stable operation.
1, 8	DGND1	—	0V		Digital GND for internal circuits.
2, 7	DGND2	—	0V		Digital GND for output transistors.
12, 29	DVEE	—	-5.2V		Digital VEE. Connected internally with AVEE. (Resistance is 4 to 6 Ω.) Connect to DGND through a ceramic chip capacitor of 0.1 μF or more just near the pin.

Pin No.	Symbol	I/O	Typical voltage level	Equivalent circuit	Description
30	D0	O	ECL		LSB of data output. External pull-down resistor is required.
31	D1				Data output. External pull-down resistors are required.
32	D2				
9	D3				
10	D4				
11	D5				MSB of data output. External pull-down resistor is required.
13	INV	I	ECL		Output polarity inversion input for D0 (LSB) to D5 (MSB). (Refer to the output code table.) When left open, Low level is maintained.
20	VIN	I	VRT to VRB		Analog input.

Pin No.	Symbol	I/O	Typical voltage level	Equivalent circuit	Description
18	VRB	I	-2V		Reference voltage (bottom) force; typical voltage is -2V. Connect to AGND through a ceramic chip capacitor of 0.1 μ F or more and a tantalum capacitor of 10 μ F or more just near the pin.
17	VRBS				Reference voltage (bottom) sense.
23	VRT	I	0V		Reference voltage (top) force; typical voltage is 0V. When applying a voltage other than AGND to this pin, connect to AGND through a ceramic chip capacitor of 0.1 μ F or more and a tantalum capacitor of 10 μ F or more just near the pin.
24	VRTS		Reference voltage (top) sense.		
3, 4 5, 6 14, 21	NC	—	—		Not connected. Although not connected in the IC, it is recommended that these pins should be connected to AGND or DGND on printed circuit board.

Electrical Characteristics

(Ta=25°C, AV_{EE}=DV_{EE}=-5.2V, V_{RT}=0V, V_{RB}=-2V)

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Resolution	n		6	6	6	bits
DC characteristics						
Integral linearity error	EIL	F _C =140MHz	-0.25		+0.25	LSB
Differential linearity error	EDL	F _C =140MHz	-0.25		+0.25	LSB
Analog input						
Analog input capacitance	C _{IN}	V _{IN} =-1V+0.07V _{ms}		7	18	pF
Analog input resistance	R _{IN}		300			KΩ
Input bias current	I _{IN}	V _{IN} =-1V			400	μA
Reference input						
Reference resistance	R _{REF}			200		Ω
Offset voltage V _{RT}	E _{OT}				20	mV
V _{RB}	E _{OB}				20	mV
Digital input						
Logic high level	V _{IH}		-1.13		-0.65	V
Logic low level	V _{IL}		-2.1		-1.50	V
Logic high current	I _{IH}	Apply -0.8V to input	0		50	μA
Logic low current	I _{IL}	Apply -1.6V to input	-50		50	μA
Input capacitance				7		pF
Switching characteristics						
Maximum conversion frequency	F _C	Error rate 1E-9 TPS*1	140			MSPS
Aperture jitter	T _{aj}			10		ps
Sampling delay	T _{ds}			1.5		ns
High pulse width of clock	TPW ₁		3.0			ns
Low pulse width of clock	TPW ₀		3.0			ns
Digital output						
Logic high level	V _{OH}	R _L =100Ω to -2V	-1.10		-0.65	V
Logic low level	V _{OL}	R _L =100Ω to -2V	-2.1		-1.6	V
Output delay	T _{do}	R _L =100Ω to -2V	3.0	3.6	4.2	ns
Output rise time	T _r	R _L =100Ω to -2V, 20% to 80%		0.8		ns
Output fall time	T _f	R _L =100Ω to -2V, 20% to 80%		1.0		ns
Dynamic characteristics						
Amplitude input bandwidth		f _{CLK} =140MHz, f _{IN} =69.999MHz	200			MHz
Error rate		Error Amplitude ≥ 4LSB 3dB down of fullscale input			1E-09	TPS*1
S/N ratio	SNR	f _{CLK} =140MHz, f _{IN} =1MHz		36		dB
		f _{CLK} =140MHz, f _{IN} =35MHz		34		dB
Power supply						
Supply current	I _{EE}	AV _{EE} =DV _{EE} =-5.2V	-60	-40	-25	mA
Power consumption	P _d			225		mW

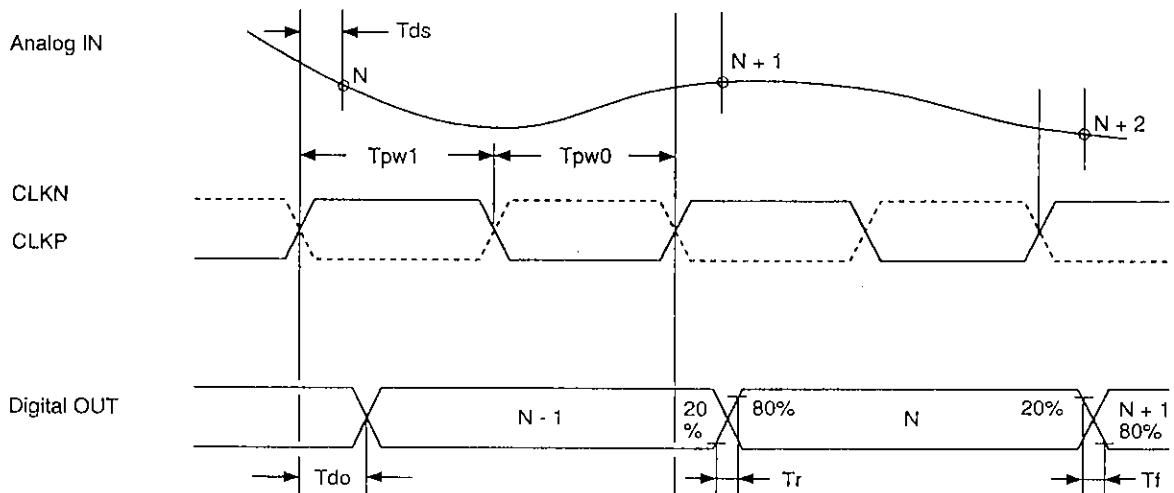
*1 TPS: Times Per Sample

Output Code Table

VIN*	Step	INV: 1		INV: 0	
		D5	D0	D5	D0
0V	0	000000	111111		
	1	000001	111110		
		⋮	⋮		
-1.0V	31	011111	100000		
	32	100000	011111		
		⋮	⋮		
-2.0V	62	111110	000001		
	63	111111	000000		

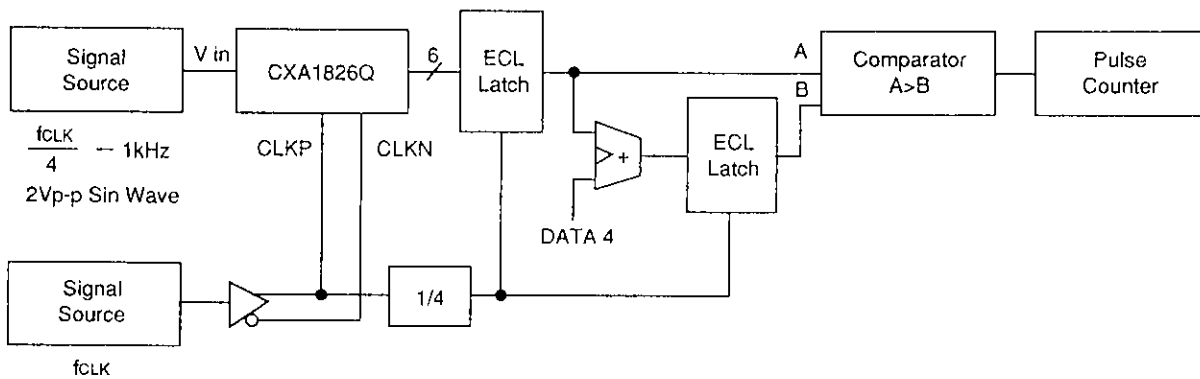
V_{RT}=0V, V_{RB}=-2V

Timing Diagram

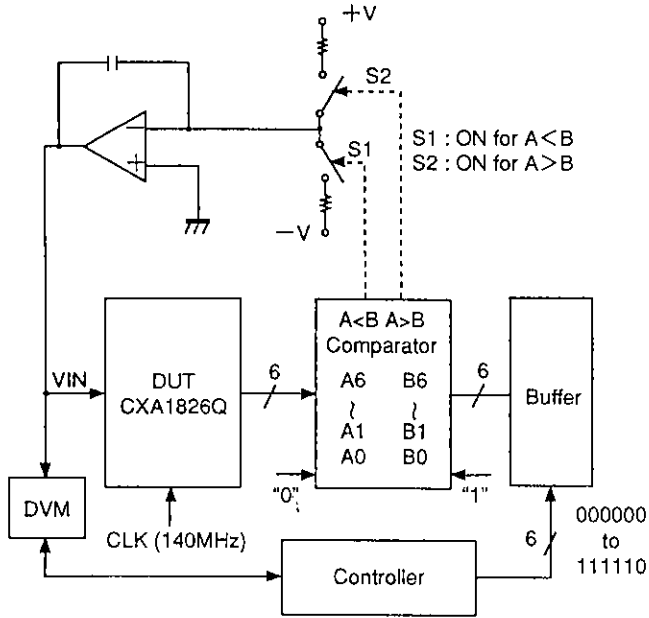


Electrical Characteristics Measurement Circuit

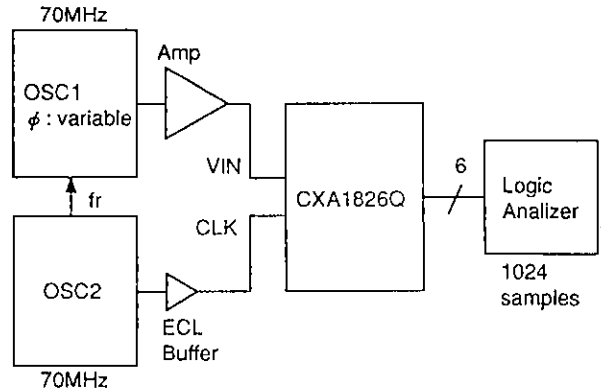
Maximum conversion rate measurement circuit



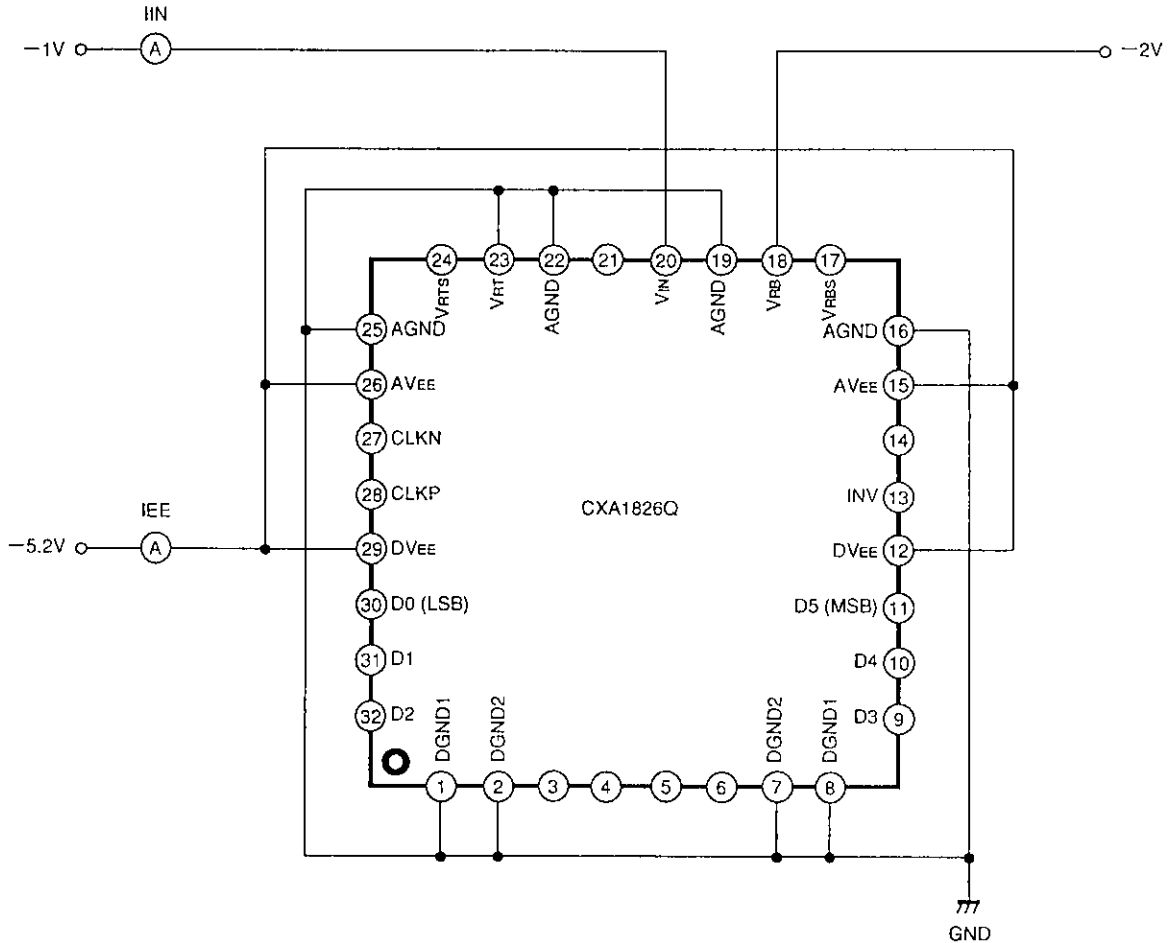
Integral linearity error measurement circuit
Differential linearity error measurement circuit



Sampling delay measurement circuit
Aperture jitter measurement circuit



Supply current measurement circuit
Analog input bias current measurement circuit



6bit, 140MHz ADC Evaluation board

Description

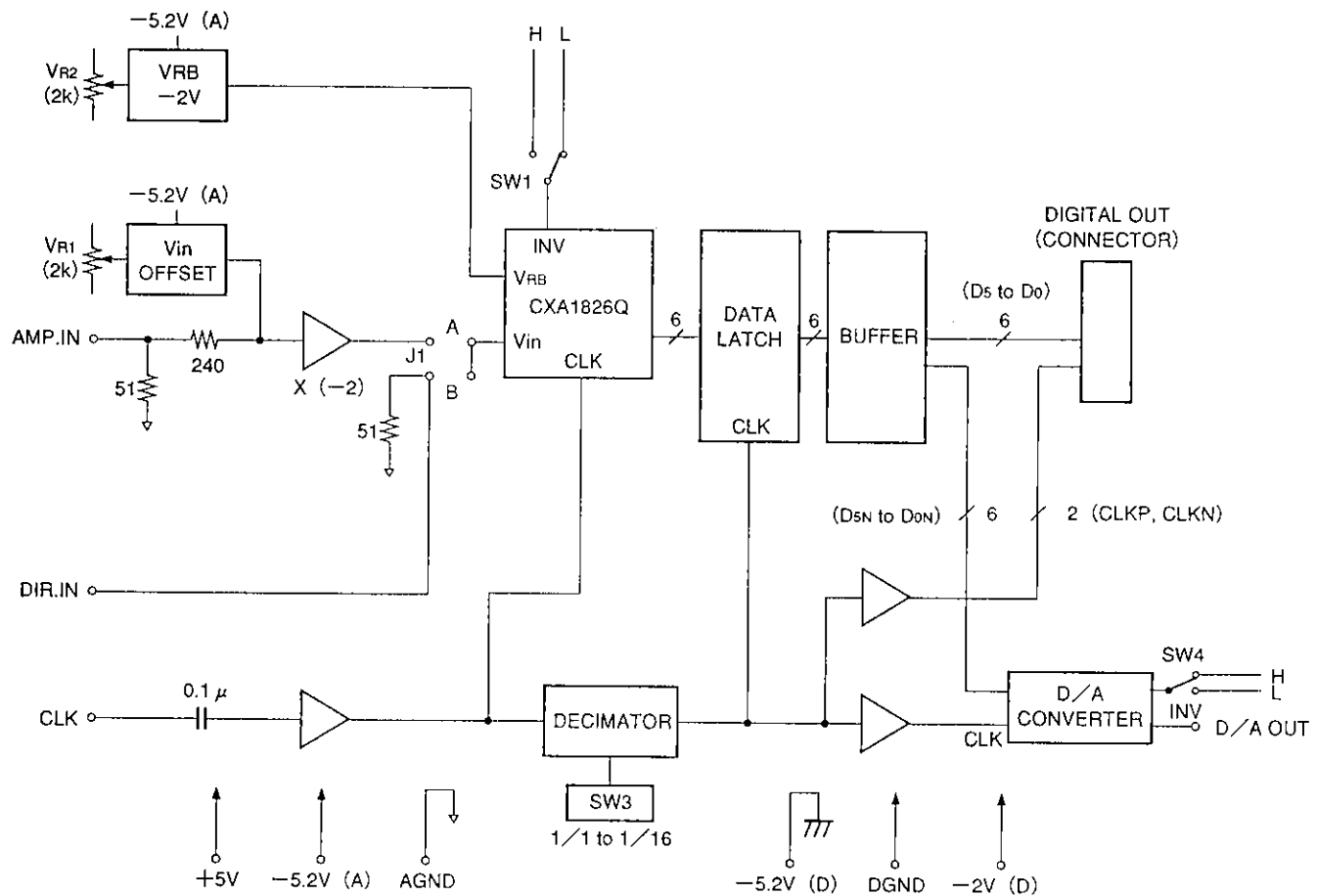
The CXA1826Q EVALUATION BOARD WITH DAC is a tool for customers to evaluate the performance of the CXA1826Q (6bit, 140MHz, high-speed A/D converter). In addition to indispensable features such as the reference voltage generator, this tool equips two sets of analog inputs (the AC coupled input and the operation amplifier input), the input voltage offset generator, the clock decimator, the output data latches, the 10-bit high-speed DAC, and the 20-pin cable connector for digital outputs.

This evaluation board provides full performance of the CXA1826Q and it is designed to facilitate evaluation.

Features

- Resolution: 6bits
- Maximum conversion rate: 140MHz
- Supply voltage: +5.0V, -5.2V, -2.0V
- Two analog inputs (AC coupled input, operation amplifier input)
- Clock level converter: Sine wave to ECL level signal
- Reference voltage adjustment circuit for the A/D converter
- Built-in clock frequency decimation circuit: (1/1 to 1/16)

Block Diagram



Supply Current

Item	Min.	Typ.	Max.	Unit
-5.2V		0.65	0.8	A
+5.0V		15	30	mA
-2.0V		0.35	0.5	A

(Note: Supply current -2.0V is the value when Rn10, Rn11 and Rn12 are not mounted.)

Analog Input (DIR. IN, AMP. IN)

Item	Min.	Typ.	Max.	Unit
Input voltage (DIR. IN)	-2.0		0	V
(AMP. IN) *1	-0.5		+0.5	V
Input impedance		50		Ω

(*1: Adjustable by VR1)

Clock Input (CLK)

Item	Min.	Typ.	Max.	Unit
Input voltage (Peak to Peak)		1.0		Vp-p
Input impedance		50		Ω

Digital Output (D0 to D5)

ECL 10kH level

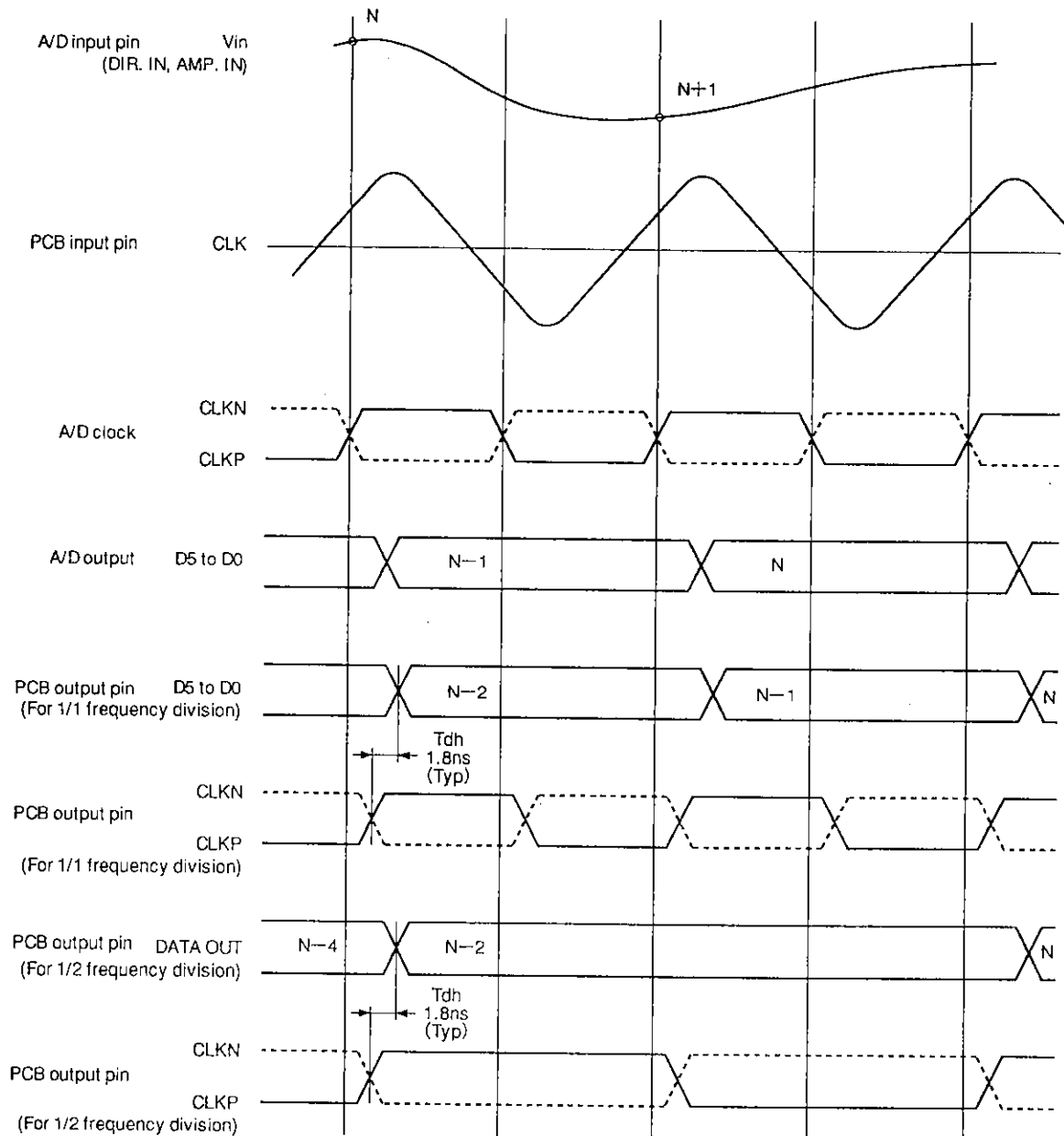
Clock Output

ECL 10kH level, complementary output

Digital Out of Connector Pin Assignment

Pin	Assignment	Pin	Assignment
1	D0 (LSB)	2	DGND
3	D1	4	DGND
5	D2	6	DGND
7	D3	8	DGND
9	D4	10	DGND
11	D5 (MSB)	12	DGND
13	NC	14	DGND
15	NC	16	DGND
17	CLKP	18	DGND
19	CLKN	20	DGND

Timing Chart



Adjustment Methods and Notes on Operation

1) V_{in} Offset (VR1)

The volume to adjust the signal range (0V center assumed) with the A/D converter input range when a waveform is input through AMP. IN.

2) A/D Full Scale (VR2)

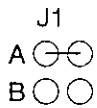
The volume to adjust A/D converter VRB voltage.

3) D/A Full Scale (VR4)
The volume to adjust D/A output full scale (-1V)

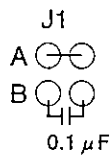
4) J1 (Input selection)
A: Shorts to select AMP.IN input.
B: Shorts to select DIR.IN input.

[Jumper Position at shipment]

When Op. Amp input is used



When AC coupled input is used



5) SW1
The switch for INV High/Low

6) SW3 (Decimation)
The switch to select clock frequency decimation.
Switch position : decimation ratio
0 : 1/1
1 : 1/2
2 : 1/4
3 : 1/8
4 : 1/16

7) SW4 (D/A INV)
The switch for D/A converter output inversion.

8) Rn10, Rn11 and Rn12 are not mounted at shipment. They are not required during evaluation.

9) Waveform probe pins P5 and P8 through P28 are devised to facilitate GND connection in order to reduce the distortion. As shown in the diagram below, the distance between the probe point and the GND is 300 mils, and there is ϕ 1.2mm throughhole at each. The signal and GND locations are suit for a Tektronix GND tip (part number 013-1185-00).

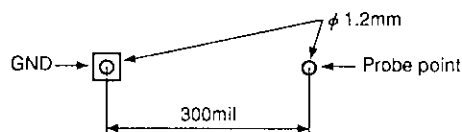
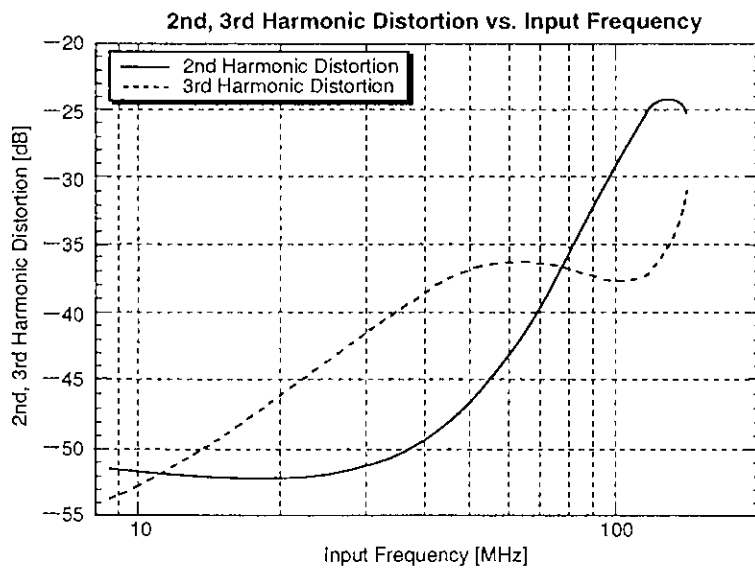
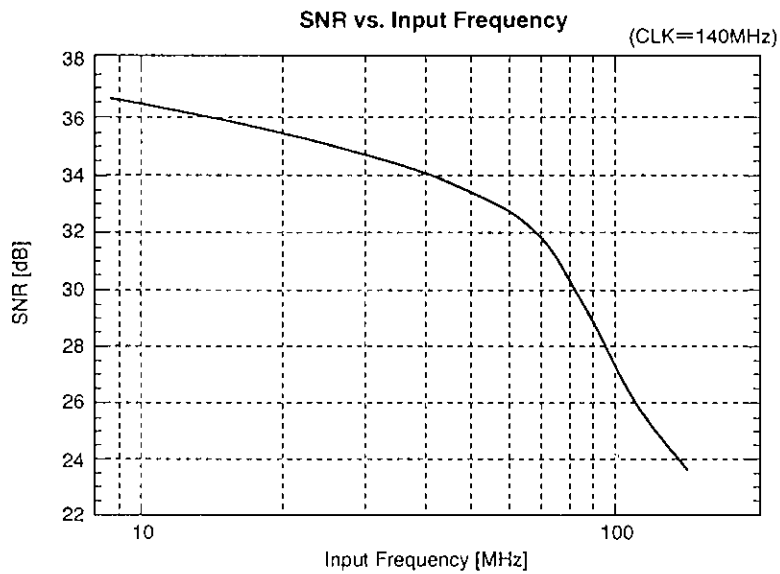
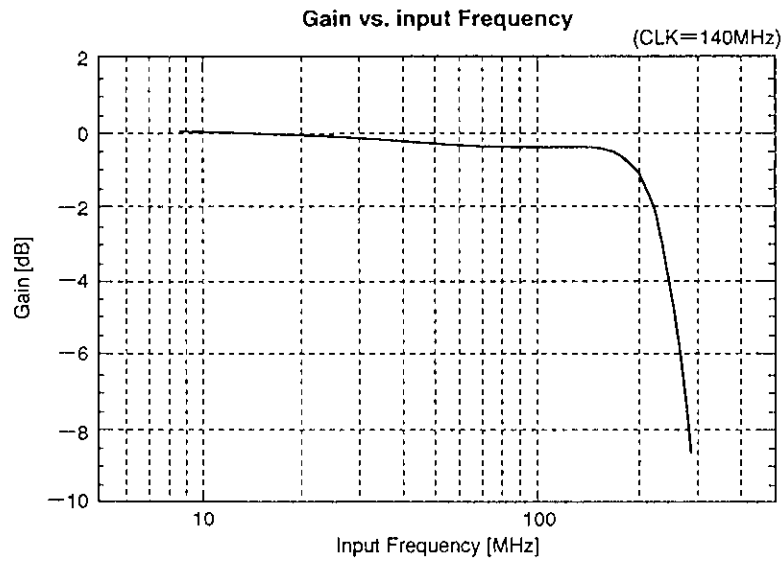


Fig. 3

10) D/A converter (IC13) input data (waveform probe pins P21 through P28) are the complementary signals of the decimated A/D converter outputs. Those are inverted again in the D/A converter so that the direction of reproduced waveform can agree with the A/D input signal converter.

Characteristics



Part List

RESISTOR:

R1, R14, R18 to R20	51 Ω
R2, R6	240 Ω
R4	22K Ω
R5	11K Ω
R7, R21	1K Ω
R8, R10	510 Ω
R9	1.3K Ω
R11	43 Ω
R15, R23	330 Ω
R16, R17	51 Ω (CHIP RESISTOR)
R22	270 Ω

TRANSISTOR:

Q1	2SA970
IC:	
IC1	TL4558P
IC2, IC8	10H116
IC3, IC14	TL431CLP
IC4	CLC404AJP
IC5	10H136
IC7	10H164
IC9, IC10	10H176
IC11, IC12	10H101
IC13	CX20202A-1

NETWORK RESISTOR:

Rn1, Rn2, Rn7	51 Ω
Rn5 to Rn9	75 Ω
Rn3, Rn4	100 Ω

DIODE:

D1 to D6	1S2076A
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VARIABLE RESISTOR:

VR1, 2, 4	2K Ω
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FERRITE BEAD:

LB1, LB2	ZBF253D-00
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CAPACITOR

C1	0.1μF (CERAMIC)
C4, C50	3.3μF (TANTALUM)
C6, C7, C15, C26	1μF (TANTALUM)
C20	10μF (TANTALUM)
C54 to C57	33μF (TANTALUM)
OTHERS	0.1μF (CHIP CAPACITOR)

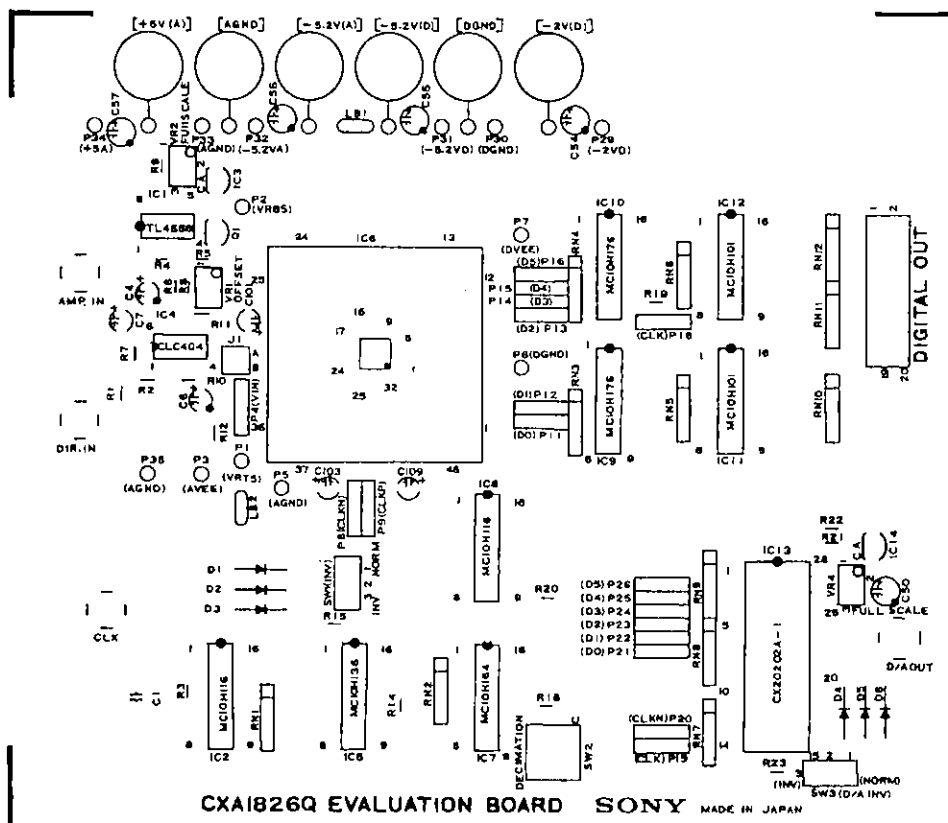
SWITCH:

SW1, SW3	ATE1D-2M3-10
SW2	S-1010A

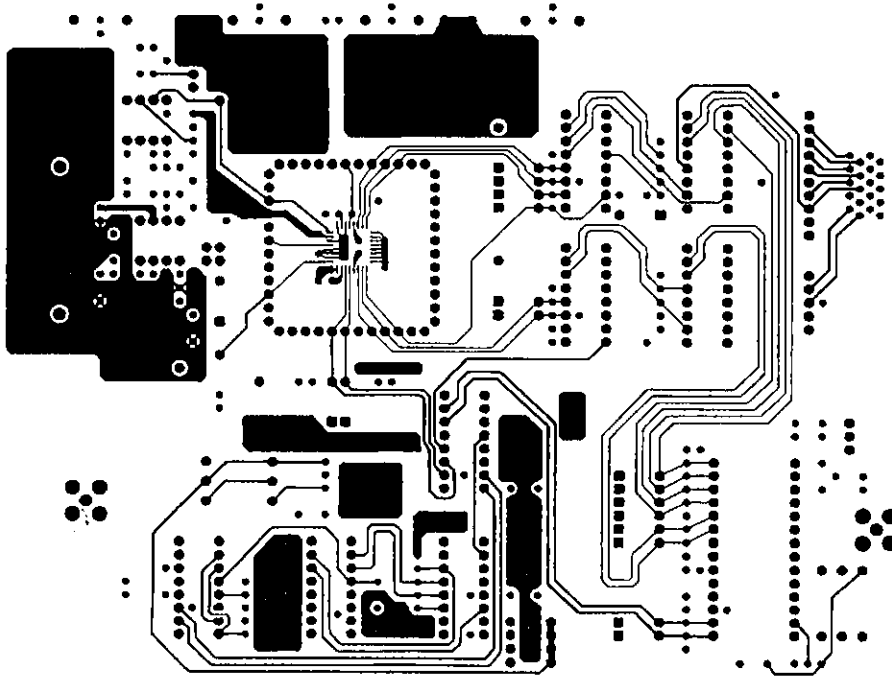
OTHERS

SMA CONNECTOR	TMA5502-10
Dout CONNECTOR	8830E-020-170S
JUMPER LINE	JX-1

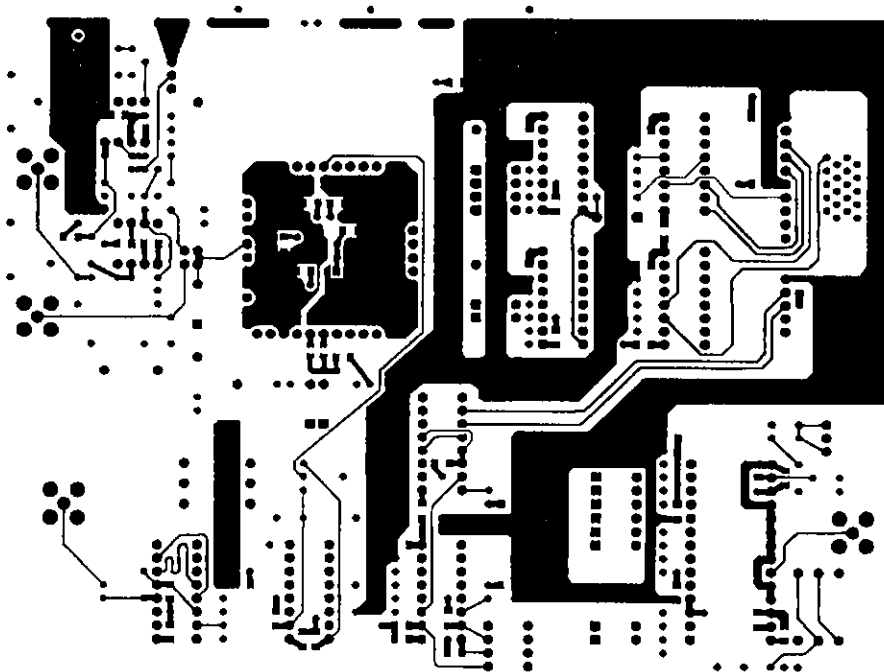
Parts Layout



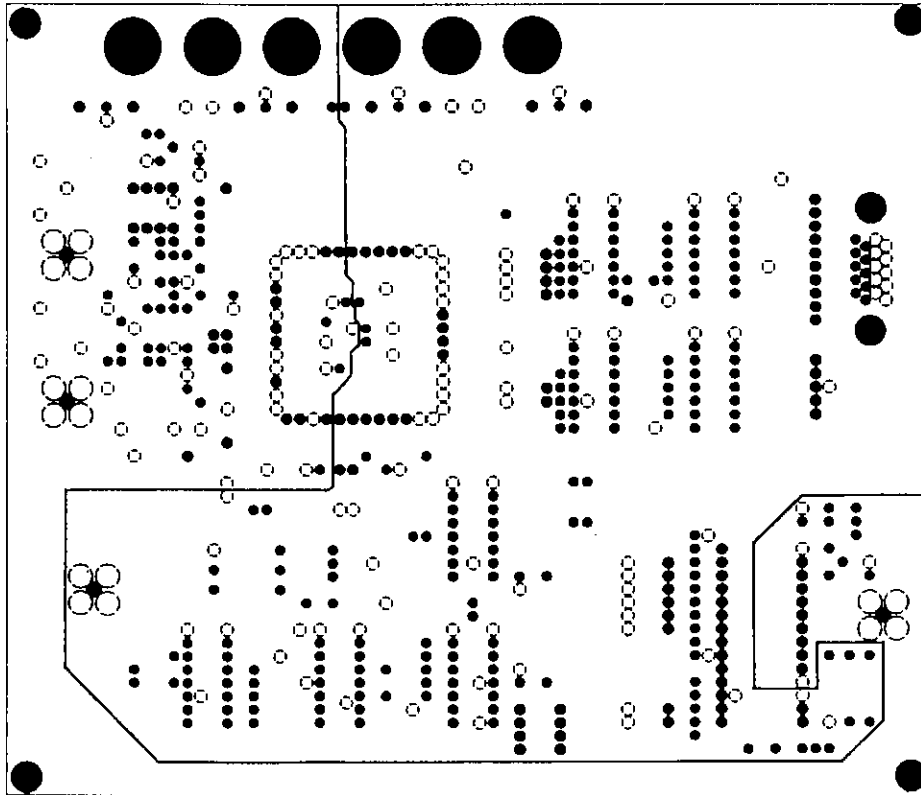
Printed Pattern



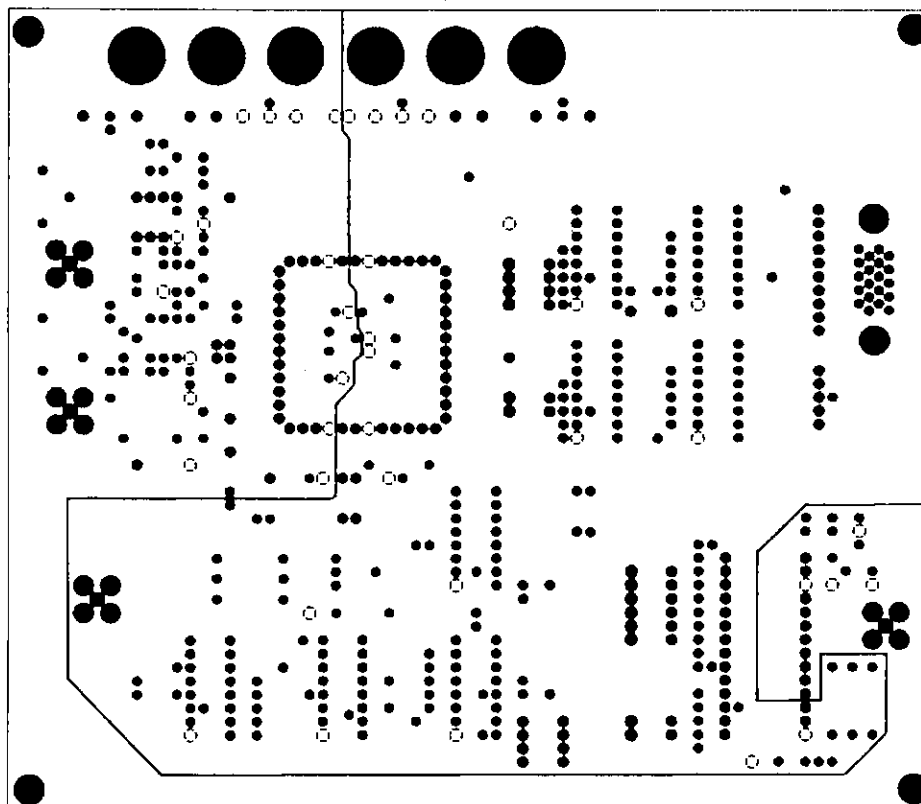
1st layer Component plane (Top View)



4th layer Solder plane (Top View)

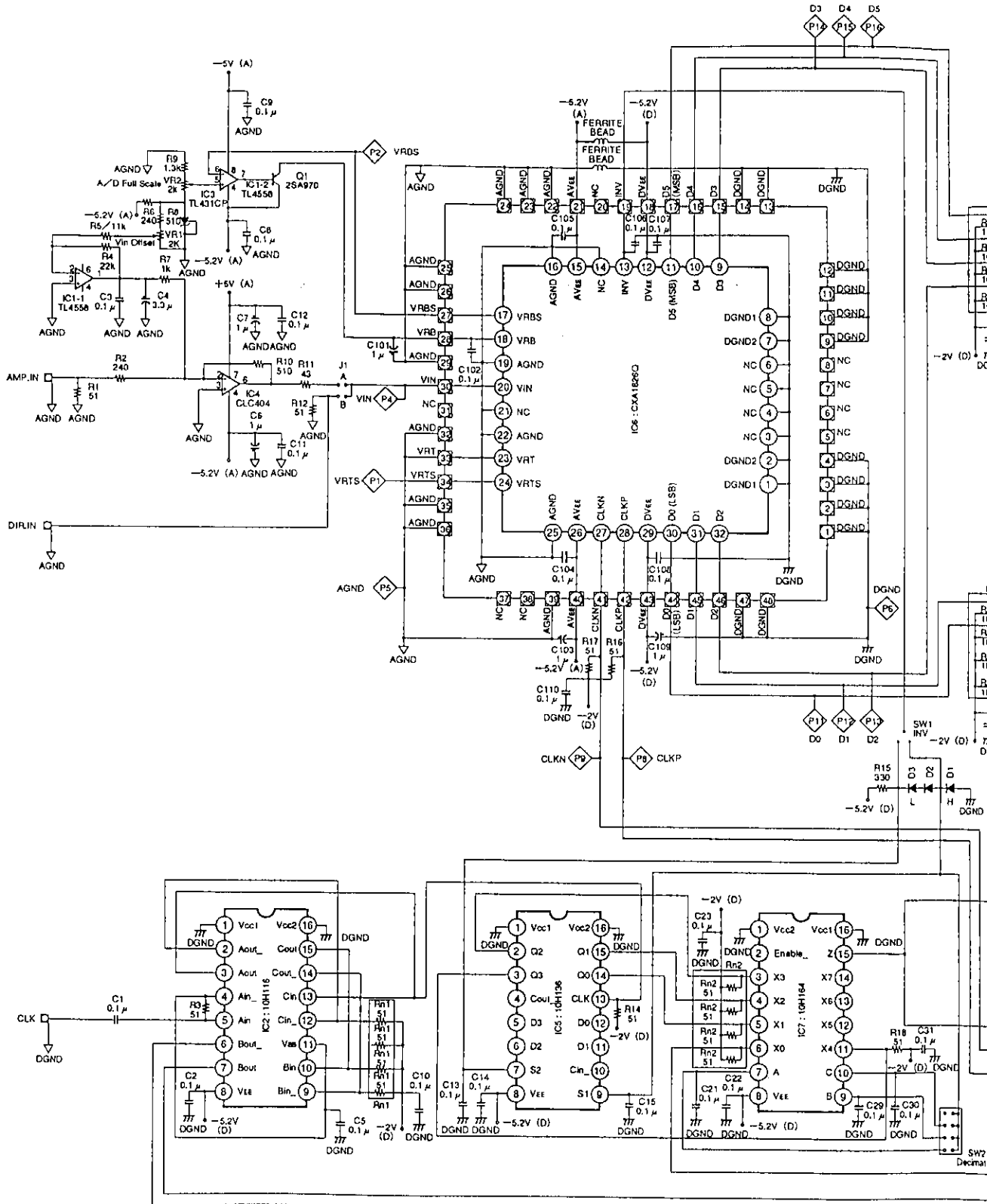


2nd layer GND plane (Top View)

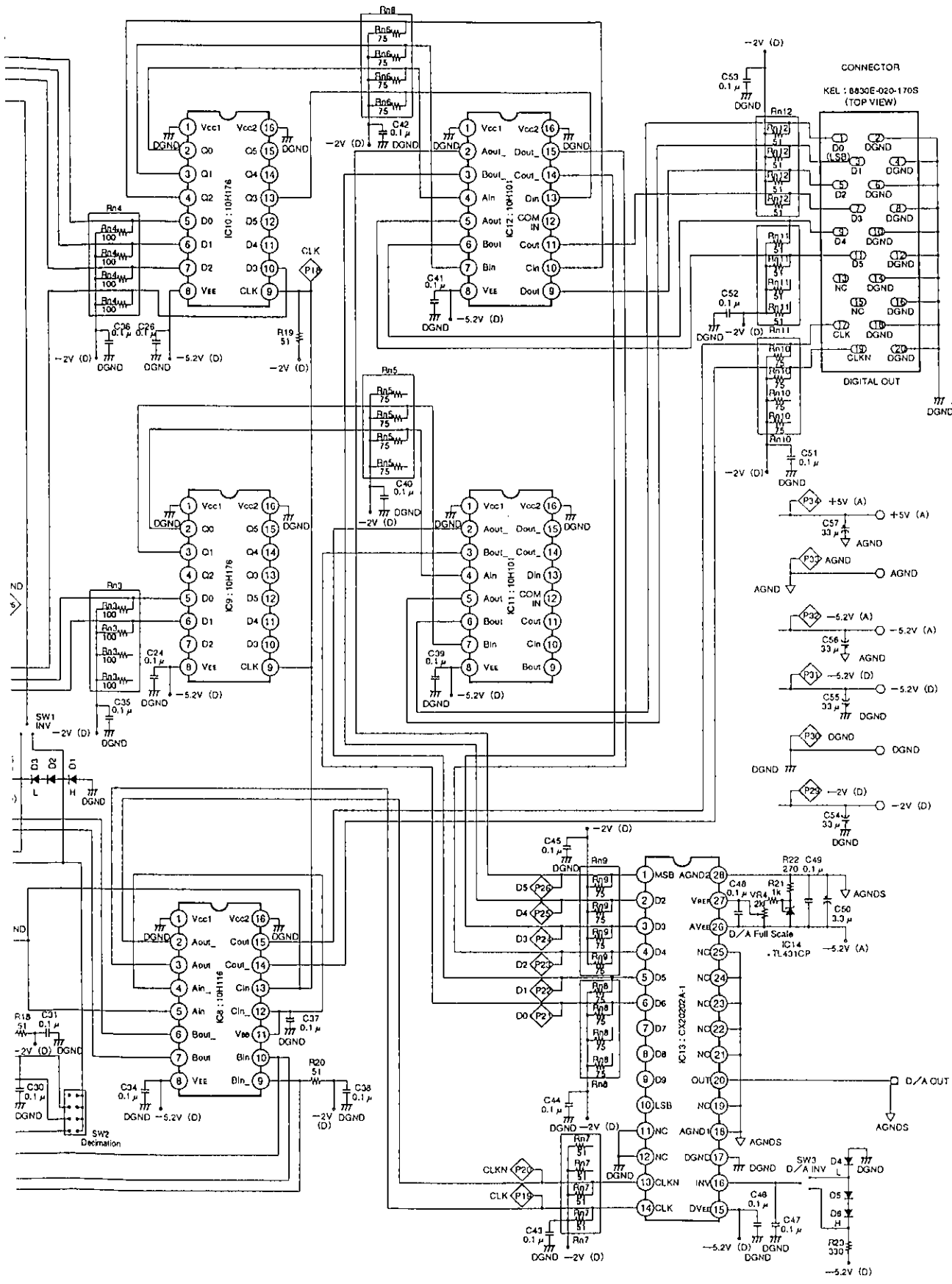


3rd layer Power supply plane (Top View)

PCB Circuit Diagram



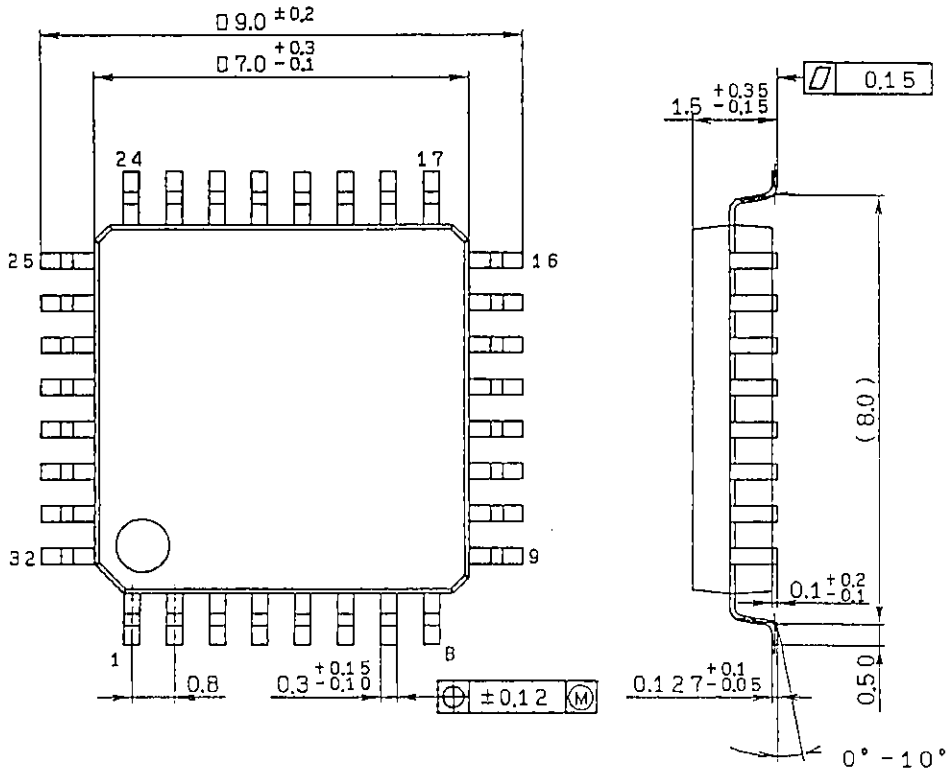
PCB Circuit Diagram shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.



Package Outline

Unit : mm

32pin QFP (Plastic) 0.2g



SONY NAME	QFP-32P-L01
EIAJ NAME	*QFP032-P-0707-A
JEDEC CODE	_____